

ABSTRACT

SEMICONDUCTOR PACKAGE HEAT GENERATION SIMULATION UNIT FOR CHECKING HEAT DISTRIBUTION OF BURN-IN BOARD AND METHOD FOR ACQUIRING HEAT DISTRIBUTION OF BURN-IN BOARD USING THE SAME

Provided are a semiconductor package heat generation simulation unit for checking heat distribution of a burn-in board and a method for acquiring heat distribution of a burn-in board using the same, the unit including: a circuit board including input/output terminals each corresponding to a conductive part of a socket of the burn-in board, and a power terminal and a signal terminal, connected to the input/output terminals; a heater configured to generate heat by power input through the power terminal; and a temperature sensor configured to measure a temperature of heat generated by the heater and output temperature information on the temperature through the signal terminal.